

APPLICATIONS

- USB 2.0 Power and Data Line Protection.
- Video Graphics Cards.
- Monitors and Flat Panel Displays.
- Digit Video Interface.
- 10/100 Ethernet.
- Notebook Computers.
- SIM Pots.
- ATM Interfaces.



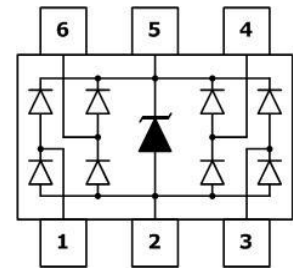
SOT23-6

MECHANICAL CHARACTERISTICS

- JEDEC SOT23-6 Package.
- Molding Compound Flammability Rating: UL 94V-O.
- Weight 16 Milligrams (Approximate).
- Quantity per Reel: 3000pcs.
- Reel Size: 7inch.
- Lead Finish: Lead Free.

IEC COMPATIBILITY

- IEC61000-4-2(ESD)±15KV(air), ±8KV(contact).
- IEC61000-4-4(EFT) 40A (5/50ns).
- IEC61000-4-5(Lightning) 12A (8/20µs).



PIN CONFIGURATION

FEATURES

- Protect four I/O lines.
- Low clamping voltage.
- Working voltage: 5V.
- Low leakage current

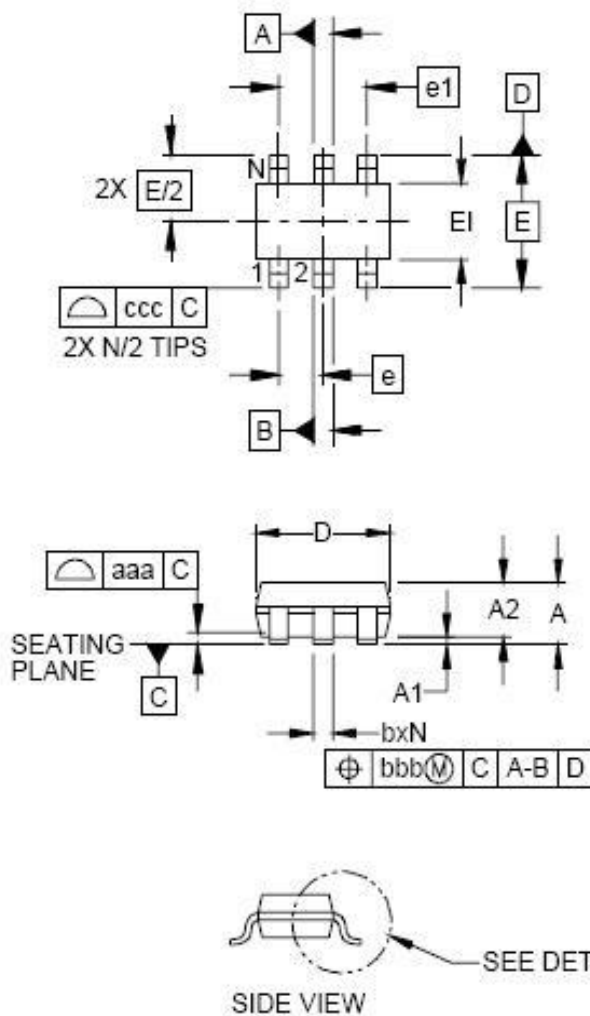
DEVICE CHARACTERISTICS

MAXIMUM RATINGS (@25°C Unless Otherwise Specified)			
PARAMETER	SYMBOL	VALUE	UNITS
Lead Soldering Temperature	T _L	260(10sec)	°C
Operating Temperature Range	T _J	-55 to +150	°C
Storage Temperature Range	T _{STG}	-55 to + 150	°C

ELECTRICAL CHARACTERISTICS PER LINE (@25°C Unless Otherwise Specified)

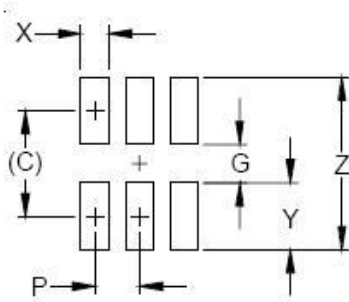
Part Number	IDRM@VDRM		VBR@IBR		VC@IPP		Co
	uA	V	V	mA	V	A	pF
	Max		MIN		MAX		TYP
SRV05-4	0.5	5.0	6.0	1.0	15.0	1.0	3

PRODUCT DIMENSIONS



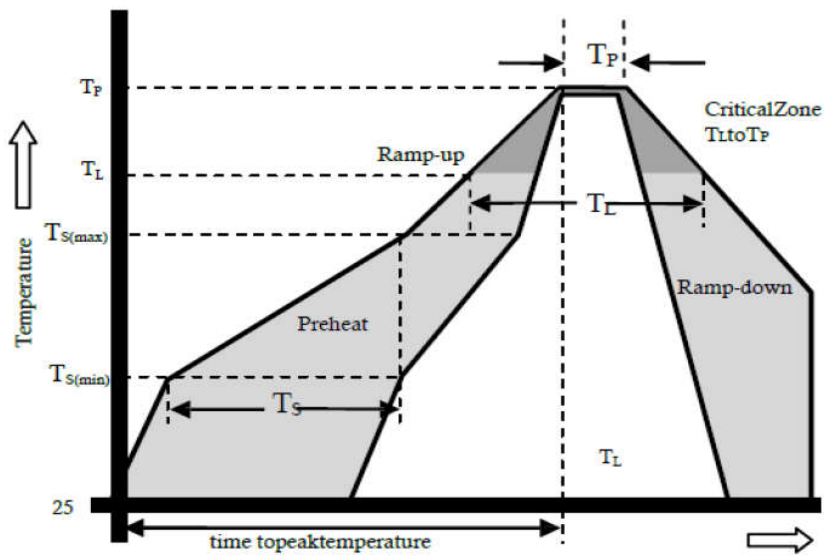
DIM	INCHES			MILLIMETERS		
	MIN	NOM	MAX	MIN	NOM	MAX
A	.035	-	.057	0.90	-	1.45
A1	.000	-	.006	0.00	-	0.15
A2	.035	.045	.051	.90	1.15	1.30
b	.010	-	.020	0.25	-	0.50
c	.003	-	.009	0.08	-	0.22
D	.110	.114	.122	2.80	2.90	3.10
E1	.060	.063	.069	1.50	1.60	1.75
E	.110 BSC			2.80 BSC		
e	.037 BSC			0.95 BSC		
e1	.075 BSC			1.90 BSC		
L	.012	.018	.024	0.30	0.45	0.60
L1	(.024)			(0.60)		
N	6			6		
theta1	0°	-	10°	0°	-	10°
aaa	.004			0.10		
bbb	.008			0.20		
ccc	.008			0.20		

SOLDERING FOOTPRINT



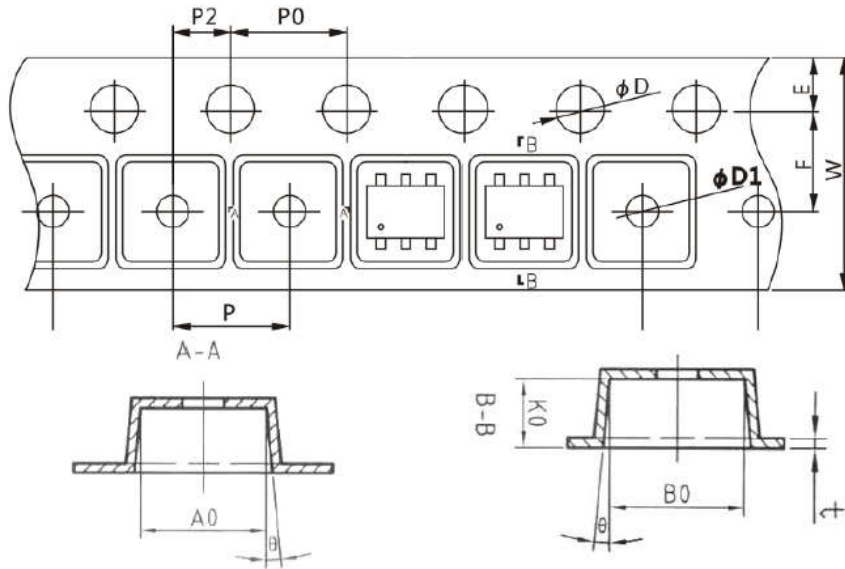
DIMENSIONS		
DIM	INCHES	MILLIMETERS
C	(.098)	(2.50)
G	.055	1.40
P	.037	0.95
X	.024	0.60
Y	.043	1.10
Z	.141	3.60

REFLOW PROFILE

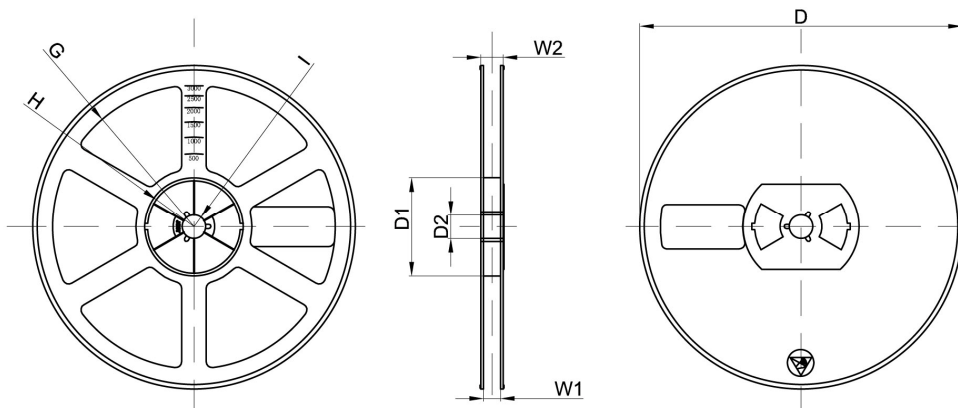


Reflow Condition		Pb-Free Assembly
Pre Heat	Temperature Min	150°C
	Temperature Max	200°C
	Time (Min to Max)	20 – 80 secs
Average ramp up rate (Liquid) Temperature (T _L) to peak		3°C/s Max.
T _S (Max) to T _L -Ramp-up Rate		3°C/s Max.
Reflow	-Temperature (T _L) (Liquid)	217°C
	-Temperature (T _L)	60 – 150 secs
Peak Temperature (T _P)		(260+0/-5)°C
Time within 5°C of actual Peak Temperature (T _P)		8– 15 secs
Ramp-down Rate		6°C/s Max.
Time 25°C to peak Temperature (T _P)		8 min Max
Do not exceed		260°C

PACKAGING



REF.	mm	REF.	mm
E	1.75±0.10	W	8.0±0.1
F	3.5±0.05	P	4.0±0.1
P2	2.0±0.05	A0	3.26±0.1
D	1.55±0.10	B0	3.3±0.1
D1	1.05±0.05	K0	1.05±0.05
P0	4.0±0.1	t	0.25±0.02
10P0	40.0±0.2	ϕ	5°



Dimensions are in millimeter								
Reel Option	D	D1	D2	G	H	I	W1	W2
7" Dia	Φ178.00	54.40	13.00	R78	R25.60	R6.50	9.50	12.3
Tolerance	±2	±1	±1	±1	±1	±1	±1	±1